



KING CORE ELECTRONICS INC.

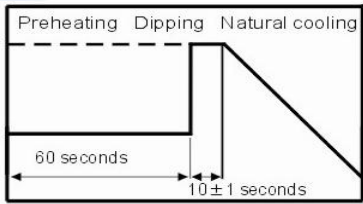
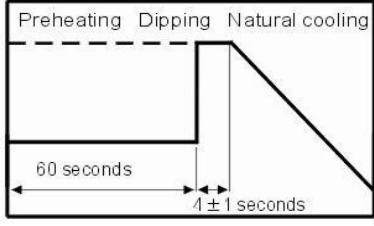
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RELIABILITY TEST – BS / BSF SERIES

1-1 Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Vibration	Appearance: No damage L change: within $\pm 10\%$ Q change: within $\pm 30\%$	Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-2	Resistance to Soldering Heat	Appearance: No damage	Preheat: 150°C , 60 seconds Solder: temperature: $260 \pm 5^{\circ}\text{C}$ Flux: Rosin Dip time: 10 ± 1 seconds 
1-1-3	Solderability	The electrodes shall be at least 90% covered with new solder coating	Preheat: 150°C , 60 seconds Solder: temperature: $245 \pm 5^{\circ}\text{C}$ Flux: Rosin Dip time: 4 ± 1 seconds 

1-2 Environmental Performance

No	Item	Specification	Test Method									
1-2-1	Thermal Shock	Appearance: No damage L change: within $\pm 10\%$ Q change: within $\pm 30\%$	One cycle: <table border="1" data-bbox="817 1798 1278 1933"> <thead> <tr> <th>Step</th> <th>Temperature ($^{\circ}\text{C}$)</th> <th>Time (min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40 ± 3</td> <td>30</td> </tr> <tr> <td>2</td> <td>85 ± 2</td> <td>30</td> </tr> </tbody> </table> Total: 100cycles Measured after exposure in the room condition for 24hrs	Step	Temperature ($^{\circ}\text{C}$)	Time (min)	1	-40 ± 3	30	2	85 ± 2	30
Step	Temperature ($^{\circ}\text{C}$)	Time (min)										
1	-40 ± 3	30										
2	85 ± 2	30										

※All the data listed in this catalogue are for reference only, King Core reserves the right to alter or revise the specifications without prior notification.

W006.A01



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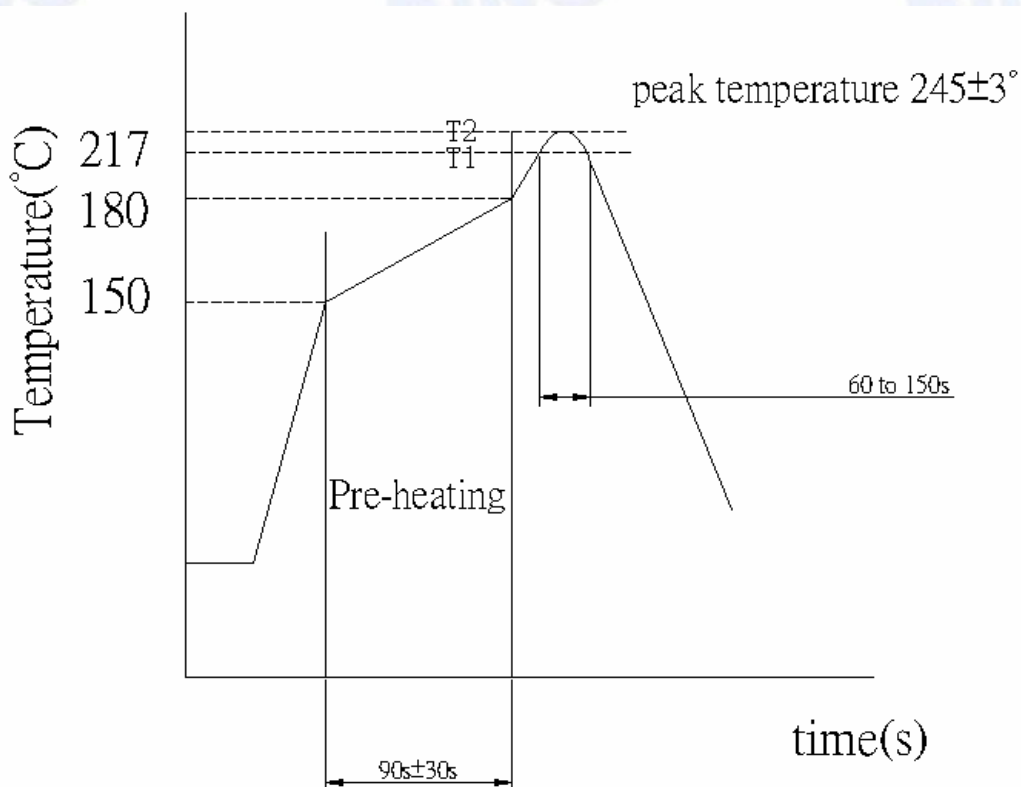
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1-2-2	Humidity Resistance		Temperature: $40\pm 2^{\circ}\text{C}$ Relative Humidity: 90 ~ 95% Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: $85\pm 3^{\circ}\text{C}$ Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: $-25\pm 3^{\circ}\text{C}$ Relative Humidity: 0% Time: 1000hrs Measured after exposure in the room condition for 24hrs

1-3 Recommended Reflow Soldering profile



Note

1. Operating Temperature Range: -25°C to $+85^{\circ}\text{C}$
2. Storage Temperature Range: -40°C to $+85^{\circ}\text{C}$ (For products in unopened tape package 0°C to $+40^{\circ}\text{C}$)

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